

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,998,711 B1
APPLICATION NO. : 09/638026
DATED : February 14, 2006
INVENTOR(S) : Paul A. Farrar

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page,

Item [54], Title, "**METHOD OF FORMING A MICRO SOLDER BALL FOR USE IN C4 BONDING PROCESS**" should read -- **A SEMICONDUCTOR DEVICE HAVING A SOLDER BALL CONTACT** --.

Column 1,

Line 34, "have developed" should read -- have been developed --;
Line 41, "I/O Lines" should read -- I/O lines --;

Column 2,

Line 28, "a IC" should read -- an IC --;

Column 6,


Line 29, "remove" should read -- removes --; and

Column 8,

Line 10, "claim 4" should read -- claim 1 --.

Signed and Sealed this

Eleventh Day of July, 2006

A handwritten signature in black ink, appearing to read "Jon W. Dudas". The signature is stylized with a large, looped initial "J" and a distinct "D" at the end.

JON W. DUDAS

Director of the United States Patent and Trademark Office